Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2422	257/778.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 10:17
L2	657570	recess	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 10:17
L3	16894	BGA	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 10:17
L4	19166	Ball adj grid adj array$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 10:18
L5	75	1 and 2 and 3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 10:29
L6	0	die adj "with" adj recess	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 10:29
L7	0	"with" adj recess	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 10:29
L8	6	with$1 near recess	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 10:42
L9	946789	match$7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 10:42

L10	66	1 and 2 and 9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 10:49
L11	71	on adj chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 10:49
L12	0	on adj chip near recess	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 10:49
L13	0	11 and recess	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 10:50
L14	340	PCB with projections	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 10:51
L15	1	14 and flip-chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 10:53
L16	38	With$1 with recess	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 10:53
L17	2	16 and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 10:54
L18	223	1 and 2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 11:09
L19	1	"6437451".PN.	USPAT; USOCR	OR	OFF	2005/06/01 10:58
L20	1	"6376915".PN.	USPAT; USOCR	OR	OFF	2005/06/01 10:59
L21	1	"6376915".PN.	USPAT; USOCR	OR	OFF	2005/06/01 11:05

L22	1	"6180261".PN.	USPAT; USOCR	OR	OFF	2005/06/01 11:06
L23	1	"5926694".PN.	USPAT; USOCR	OR	OFF	2005/06/01 11:07
L24	1	"5864178".PN.	USPAT; USOCR	OR	OFF	2005/06/01 11:07
L25	27	14 and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 11:15
L26	6	14 and flip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 11:09
L27	75451	PCB	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 11:15
L28	3	protruded adj solder adj ball$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 11:16
L29	22801	solder adj ball$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 11:16
L30	622947	protrud$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 11:16
L31	1121	29 same 30	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 11:17
L32	813	31 and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 11:18
L33	772	29 with 30	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 11:18

L34	3	1 and 2 and 33	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 11:19
L35	1554	akram.inv.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 11:20
L36	62	35 and 1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 11:27
L37	20715	bond near pad$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 11:28
L38	310940	concave	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 11:28
L39	82	38 with 37	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 12:02
L40	8	39 and BGA	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 11:46
L41	3891	concave with pad$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 12:02
L42	121	41 and BGA	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 12:47
L43	26755	flip adj chip$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 12:48

L44	23564	3 4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 12:48
L45	5996	43 and 44	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 12:48
L46	53	41 and 45	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 13:00
L47	294557	stacked	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 13:00
L48	294	41 and 47	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 13:05
L49	45	48 and bga	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 13:01
L50	125	48 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 13:09
L51	37	negative with BGA	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 13:26
L53	8	socket adj grid adj array	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 13:28
L54	138	41 and (flip adj chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 13:55

L55	1891	257/737.CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 13:55
L56	32	41 AND 55	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 13:59
L57	0	solder adj hole$1 adj array	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/01 14:00